

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Previously Presented) A method of bonding a first object having a polymer surface together with a second object having an electrically conductive or semiconductive surface, the method comprising the steps of:
 - a) electrografting an organic film onto the conductive or semiconductive surface of the second object; and then
 - b) bonding the polymer surface of the first object to the conductive or semiconductive surface of the second object thus grafted.
2. (Previously Presented) The method as claimed in claim 1, in which the electrografting of the organic film is electroinitiated grafting.
3. (Previously Presented) The method as claimed in claim 2, in which the organic film is a polymer film.
4. (Previously Presented) The method as claimed in claim 3, in which the polymer film is obtained from compounds selected from the group consisting of monomers and prepolymers that are partly or completely functionalized by vinyl groups.
5. (Previously Presented) The method as claimed in claim 4, in which the polymer film is obtained from a vinyl monomer selected from the group consisting of acrylonitrile, methacrylonitrile, acrylates and methacrylates, acrylamides, methacrylamides, cyanoacrylates, acrylic acid, methacrylic acid, styrene, vinyl halides, N-vinylpyrrolidone, 2 vinylpyridine, 4 vinylpyridine and vinyl-terminated telechelic compounds.

6. (Previously Presented) The method as claimed in claim 3, in which the polymer film is obtained from compounds selected from the group consisting of monomers and prepolymers that are partly or completely functionalized by cyclic groups that can be cleaved by nucleophilic or electrophilic attack.

7. (Previously Presented) The method as claimed in claim 2, in which the organic film is obtained from diazonium, sulfonium, phosphonium or iodonium salts, or mixtures thereof.

8. (Previously Presented) The method as claimed in claim 1, in which the bonding consists of hotmelt bonding or cold bonding or a combination thereof.

9. (Previously Presented) The method as claimed in claim 8, in which the cold bonding is carried out by means of a substance capable of dissolving or swelling the polymer surface to be bonded and the organic film electrografted onto the conductive or semiconductive surface.

10. (Previously Presented) The method as claimed in claim 1, in which the polymer constituting the polymer surface is selected from the group consisting of polyethylenes, polypropylenes, polystyrenes, polyacrylonitriles, polysiloxanes, polyesters, polyorthoesters, polycaprolactones, polybutyrolactones, polyacrylics, polymethacrylics, polyacrylamides, epoxide resins, copolymers thereof and blends thereof.

11. (Previously Presented) The method as claimed in claim 1, in which the polymer constituting the polymer surface is a hotmelt polymer.

12. (Previously Presented) The method as claimed in claim 1, in which the polymer surface is a polymer film coating a conductive or semiconductive material.

13. (Withdrawn) A method of manufacturing or renovating composites intended for the aerospace, aeronautical, automotive, biomedical, microelectronics and microsystems industries, which comprises a step consisting in bonding two objects together by the method of claim 1.

14. (Withdrawn) A method of manufacturing implantable surgical and medical instruments, which comprises a step consisting in bonding two objects together by the method of claim 1.

15. (Withdrawn) A method of assembling sensitive components of microsystems which comprises a step consisting in bonding two objects together by the method of claim 1.

16. (Withdrawn) A structure comprising two objects, one of which has an electrically conductive or semiconductive surface and the other has a polymer surface, these surfaces being bonded to each other via an organic film with a thickness of less than 1 μm .

17. (Withdrawn) A method of packaging of Microsystems, which comprises a step consisting in bonding two objects together by the method of claim 1.

18. (New) The method as claimed in claim 1, in which the organic film has a thickness of between 50 and 300 nm.